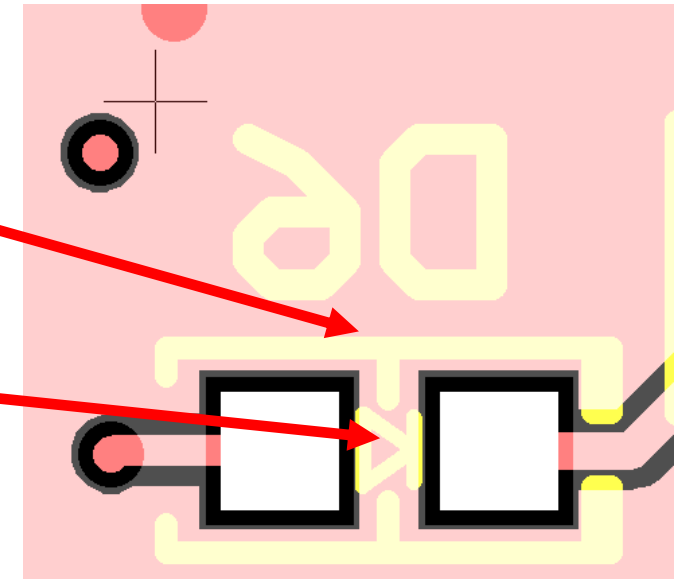


Bottom Side

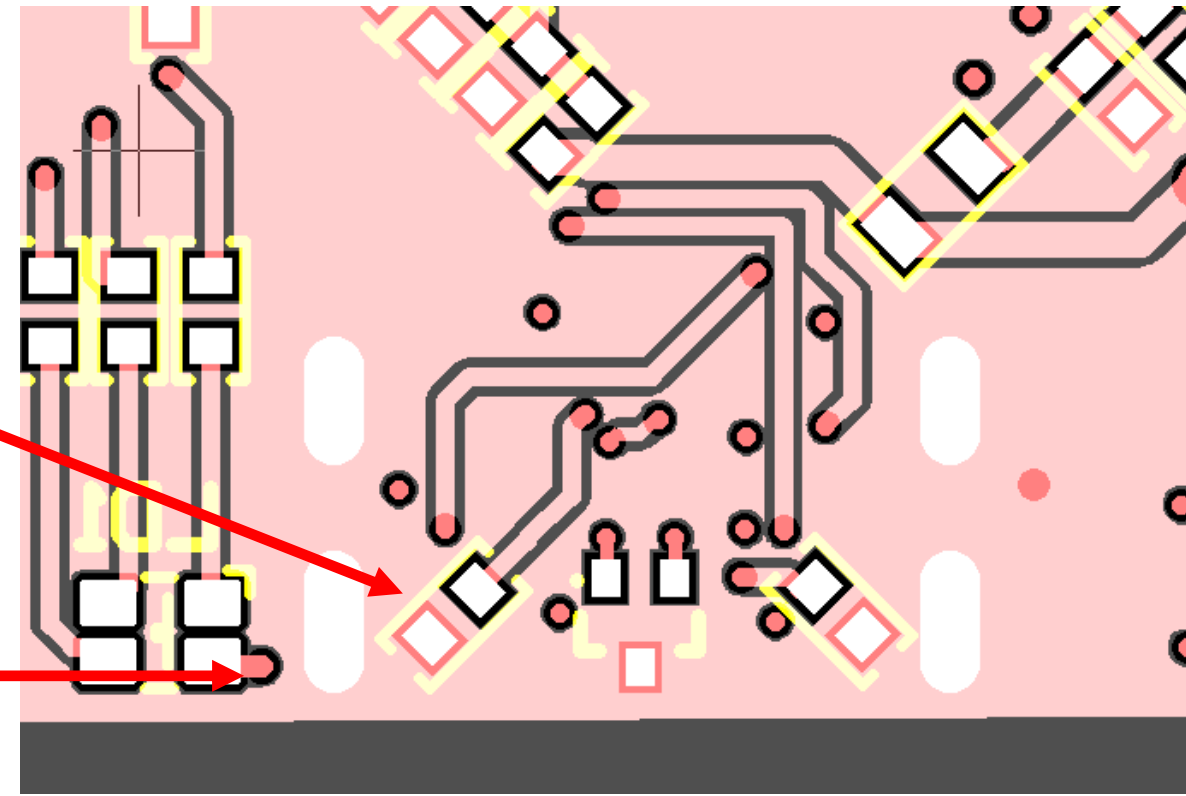
Move the polarity indicator to outside of the component footprint. Allows for verification post placement.

To Here

From here

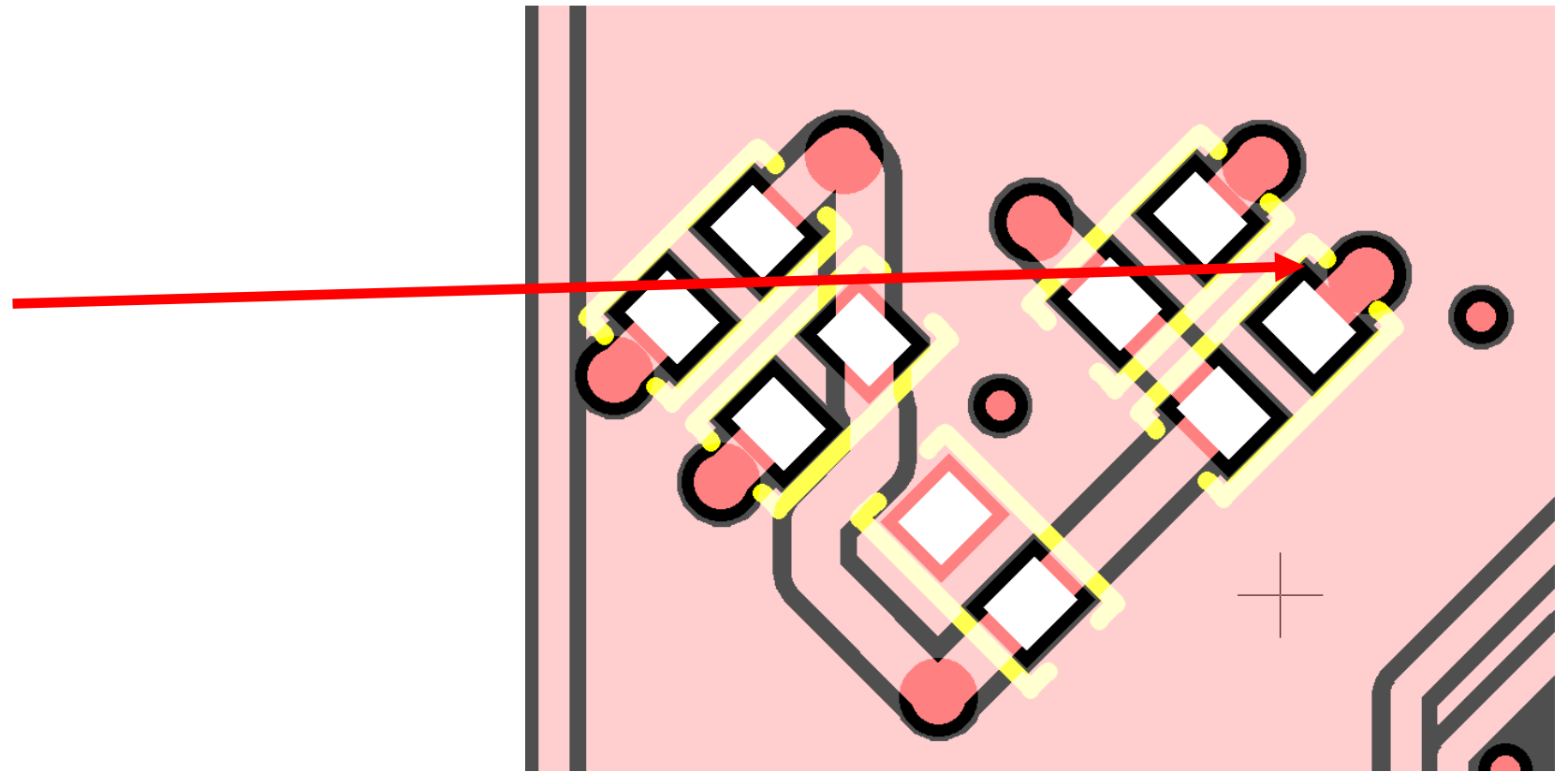


Move SMT parts away from the THT pads, potential interference with Selective solder. There are several locations, samples shown here.
Prefer .25" clearance, if possible, otherwise please provide as much clearance as the design will allow.



Bottom Side

Fab drawing says to fill and cap vias that are in SMT pads, however some vias are pad adjacent with little or no SM web. Its unclear if these vias will be tented, if so no issue. Otherwise ask to tent vias or fill and cap all vias.

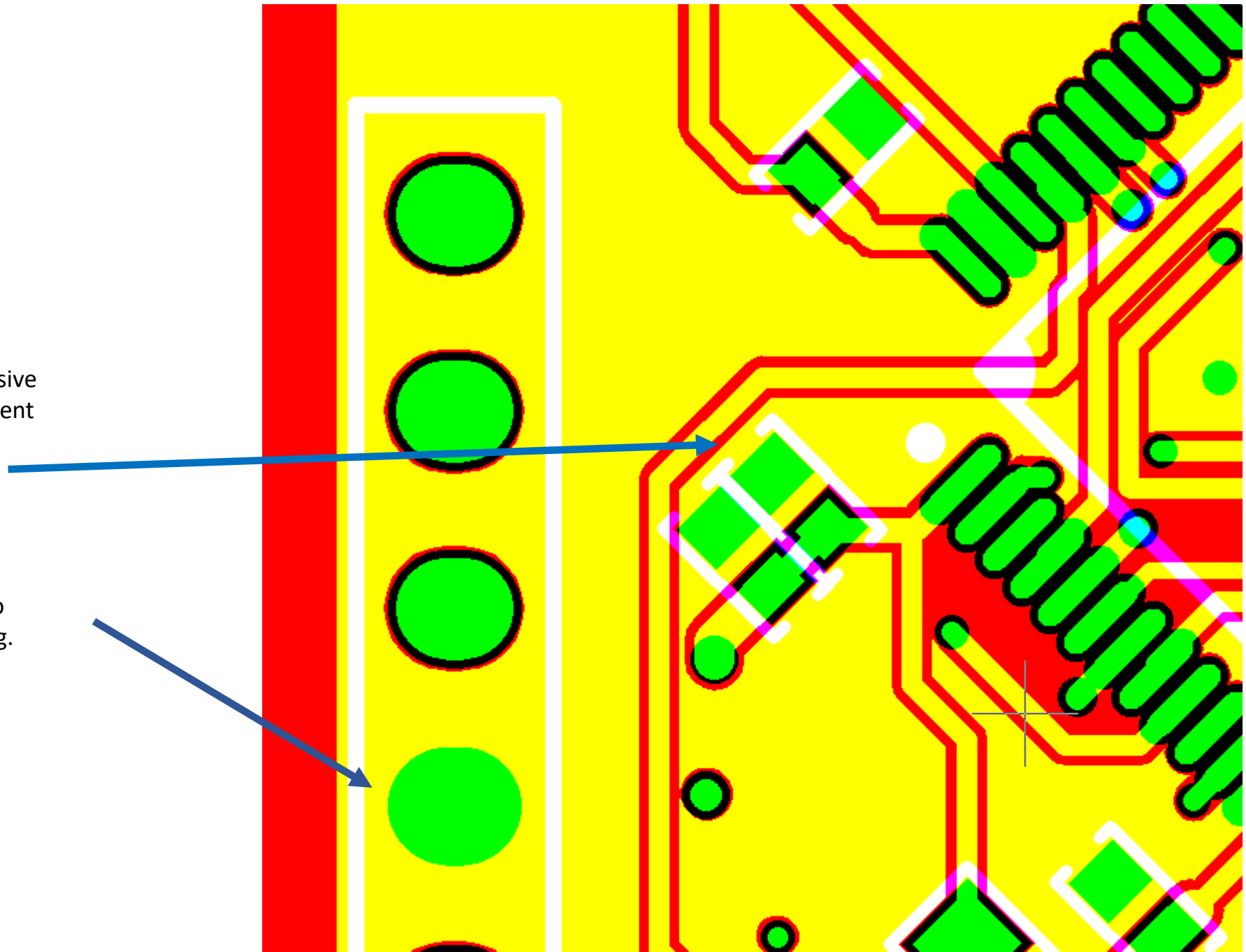


Top Side

There are many instances of thermal relief issues, only a few examples shown here.

Adding thermals to balance the CU on passive components is recommended to help prevent tombstones.

Add thermal relief wherever possible to promote equalized reflow and soldering.



Top Side

There are many instances of thermal relief issues, only a few examples shown here.

